

ON Semiconductor				10/15/2019
Base Part		FAN2558	HF	Pb-free
Orderable Part		FAN2558MPX	Total weight (mg)	9.44
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	0.6023	Silicon (Si)	7440-21-3	100
Die Attach	0.0776	Bis(a,a-dimethylbenzyl) Peroxide	80-43-3	0.51546392
		Isobornyl Methacrylate	7534-94-3	5.54123711
		Silver (Ag)	7440-22-4	82.86082474
		Isobornyl Acrylate	5888-33-5	5.54123711
		Tricyclo[5.2.1.02,6]decanedimethanol Diacrylate (C18H24O4)	42594-17-2	5.54123711
Lead Frame	4.0051	Zinc (Zn)	7440-66-6	0.12472383
		Iron (Fe)	7439-89-6	2.35015323
		Copper (Cu)	7440-50-8	97.44316157
		Phosphorus (P)	7723-14-0	0.08196137
Mold Compound-Black	4.612	Ortho Cresol Novolac Resin	29690-82-2	5.49869905
		Carbon Black (C)	1333-86-4	0.19947962
		Fused Silica (SiO2)	60676-86-0	75.30138768
		Phenolic Resin (Novolac)	9003-35-4	14.00043365
		Silica Crystalline (SiO2)	14808-60-7	5
Plating	0.056	Silver (Ag)	7440-22-4	3.1377551
		Palladium (Pd)	7440-05-3	3.57142857
		Nickel (Ni)	7440-02-0	92.85714286
		Gold (Au)	7440-57-5	4.00510204
Wire Bond - Cu	0.087	Copper (Cu)	7440-50-8	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels of dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				